

AK8771

Shipped in packet-tape reel(5000pcs/Reel)

AK8771 is ultra-small Hall effect IC of a single silicon chip composed of Hall element and a signal processing IC.

Bipolar Hall Effect Latch Supply Voltage 1.6~5.5V

Power down Function Ultra High Sensitivity Bop: 1.8mT

Output CMOS SON

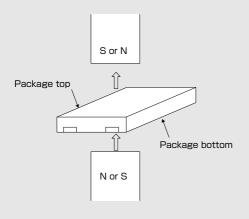
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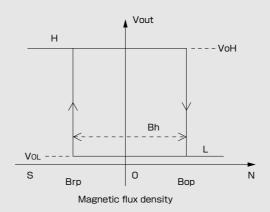
Features

- · Precision Bipolar Hall Effect Latch
- \cdot Power manageability through "PDN" pin Current consumption in Power down mode is less than $1\,\mu\text{A}$
- Ultra small SON package: 1.1×1.4×t0.37mm, Halogen free

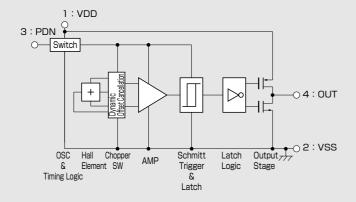


Operational Characteristics





●Functional Block Diagram



Item	Function			
osc	Generates operating clock			
Timing logic	Generates timing signal requires for Chopper SW, AMP and COMP			
Hall Element	Hall element fabricated by CMOS process			
Chopper SW	Performs chopping in order to cancel the offset voltage of Hall sensor			
AMP	Reduce offset voltage and amplifies Hall output voltage			
Schmitt Trigger	Hysteresis comparator			
Output Stage	CMOS output, During the power down mode, output is latched in its previous state			

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Absolute Maximum Ratings

Item	symbol	Min.	Max.	Unit	Note
Power supply voltage	V_{DD}	-0.3	+6.5	V	
Output current	I _{OUT}	-0.5	+0.5	mA	OUT pin
Input voltage	VIN	-0.3	V _{DD} +0.3*	V	PDN pin
Input current	IIN	-10	+10	mA	PDN pin
Storage temperature	T _{STG}	-55	+125	°C	

^{*)} Less than +6.5V.

Note) Stress beyond these listed values may cause permanent damage to the device.

Recommended Operating Conditions

Item	symbol	Min.	Typ.	Max.	Unit
Power supply voltage	V_{DD}	1.6	3.0	5.5	V
Operating temperature	Ta	-30		+85	c

●Electrical Characteristics (Ta=25°C VDD=3.0V)

Item	symbol	Min.	Тур.	Max.	Unit	Note
Current consumption 1	I _{DD1}			1	μΑ	PDN=0V
Current consumption 2	I _{DD2}		2.5	6	mA	PDN=VDD
PDN Input current	I _{IN}	-1		1	μΑ	
PDN input H voltage	V _{IH}	0.7V _{DD}			٧	
PDN input L voltage	V _{IL}			0.3	V	
High Level output voltage	V _{OH}	V _{DD} -0.4			V	I _{out} =-0.5mA
Low level output voltage	V _{OL}			0.4	V	I _{out} =+0.5mA
PDN mode transition time 1	T _{PD1}			100	μS	Active→PDN
PDN mode transition time 2	T _{PD2}			100	μS	PDN→Active

■Magnetic Characteristics① (Ta=25°C VDD=3.0V)

Item	symbol	Min.	Тур.	Max.	Unit
Operating point	B _{op}		1.8	4.0	mT
Releasing point	B_{rp}	-4.0	-1.8		mT
Hysteresis	B _h		3.6		mT

●Magnetic Characteristics② (Ta=−30°C~85°C VDD=1.6~5.5V)

Item	symbol	Min.	Тур.	Max.	Unit
Operating point	B _{op}		1.8	4.2	mT
Releasing point	B _{rp}	-4.2	-1.8		mT
Hysteresis	B _h		3.6		mT

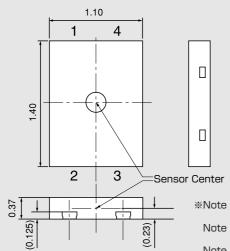
Note) The specifications in Magnetic Characteristics ② are design targets.

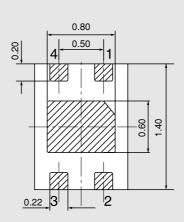
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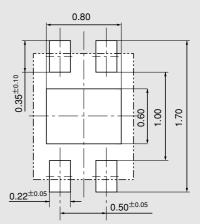
●Package (Unit:mm)





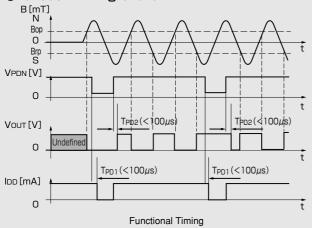
- %Note 1) Sensitive area position referenced to
 - the center of package within ϕ 0.3mm circle.
 - Note 2) Tolerances of dimension otherwise noted is ±0.05mm.
 - Note 3) Hatched area is plated.
- Note 4) Center pad area (TAB) should be tied to the VSS or floating

●Footprint (for reference)



No.	Pin name	Function	Note
1	VDD	Power supply pin	
2	VSS	Ground pin	
3	PDN	Power down pin.	CMOS Input. This pin has to be
		H:Device active	tied to "H" level when external
		L:Device power down	power control is not used.
4	OUT	Output pin	CMOS Output

Function Timing Chart

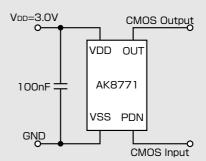


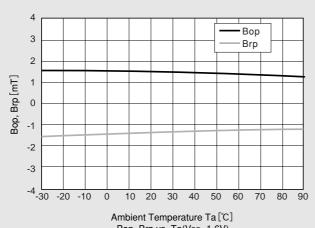
Note1) During power down mode, output is latched in its

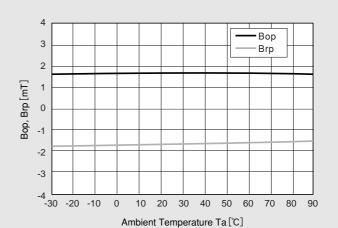
previous state.

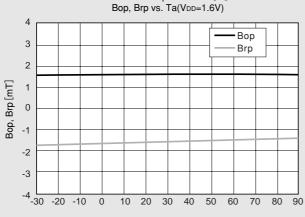
Note2) When VDD is supplied, the time from reaching VDD=1.6V to the update of the output state is equal to TPD2.

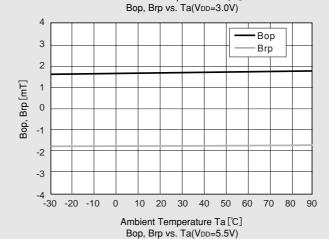
Application Circuit

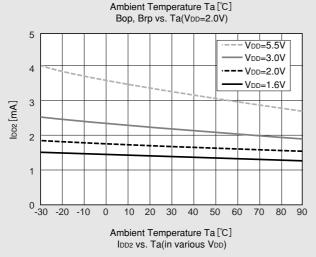


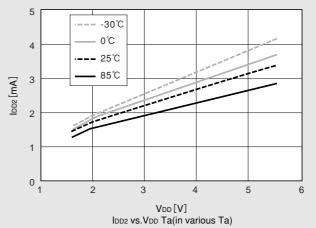












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reliability.

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